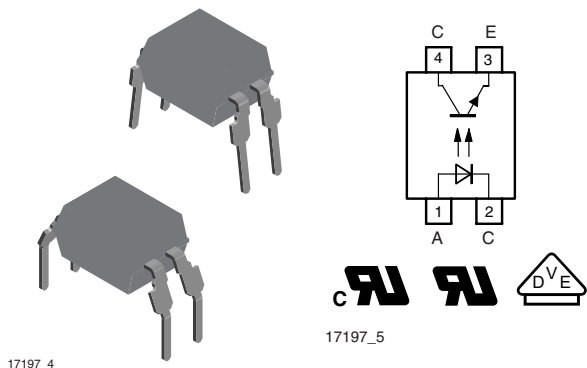


Optocoupler, Phototransistor Output, High Temperature



17197_4

17197_5

DESCRIPTION

The TCET110. consists of a phototransistor optically coupled to a gallium arsenide infrared-emitting diode in a 4-lead plastic dual inline package.

AGENCY APPROVALS

- UL1577, file no. E52744, double protection
- cUL tested, file A52744
- BSI: EN 60065:2002, EN 60950:2000
- DIN EN 60747-5-5 (VDE 0884)
- FIMKO

FEATURES

- High common mode rejection
- Low temperature coefficient of CTR
- CTR offered in 9 groups
- Reinforced isolation provides circuit protection against electrical shock (safety class II)
- Isolation materials according to UL 94 V-O
- Pollution degree 2 (DIN/VDE 0110/resp. IEC 60664)
- Climatic classification 55/100/21 (IEC 60068 part 1)
- Rated impulse voltage (transient overvoltage) $V_{IOTM} = 6 \text{ kV}_{\text{peak}}$
- Isolation test voltage (partial discharge test voltage) $V_{pd} = 1.6 \text{ kV}$
- Rated isolation voltage (RMS includes DC) $V_{IOWM} = 600 \text{ V}_{\text{RMS}}$
- Rated recurring peak voltage (repetitive) $V_{IORM} = 848 \text{ V}_{\text{peak}}$
- Creepage current resistance according to VDE 0303/ IEC 60112 comparative tracking index: $CTI \geq 175$
- Compliant to RoHS directive 2002/95/EC and in accordance to WEEE 2002/96/EC



RoHS
COMPLIANT

APPLICATIONS

Circuits for safe protective separation against electrical shock according to safety class II (reinforced isolation):

- for appl. class I - IV at mains voltage $\leq 300 \text{ V}$
- for appl. class I - III at mains voltage $\leq 600 \text{ V}$ according to DIN EN 60747-5-5 (VDE 0884), suitable for:
 - Switch-mode power supplies
 - Line receiver
 - Computer peripheral interface
 - Microprocessor system interface



TCET1100, TCET1100G

Optocoupler, Phototransistor Output, Vishay Semiconductors
High Temperature

ORDER INFORMATION	
PART	REMARKS
TCET1100	CTR 50 % to 600 %, DIP-4
TCET1101	CTR 40 % to 80 %, DIP-4
TCET1102	CTR 63 % to 125 %, DIP-4
TCET1103	CTR 100 % to 200 %, DIP-4
TCET1104	CTR 160 % to 320 %, DIP-4
TCET1105	CTR 50 % to 150 %, DIP-4
TCET1106	CTR 100 % to 300 %, DIP-4
TCET1107	CTR 80 % to 160 %, DIP-4
TCET1108	CTR 130 % to 260 %, DIP-4
TCET1109	CTR 200 % to 400 %, DIP-4
TCET1100G	CTR 50 % to 600 %, DIP-4, 400 mil
TCET1101G	CTR 40 % to 80 %, DIP-4, 400 mil
TCET1102G	CTR 63 % to 125 %, DIP-4, 400 mil
TCET1103G	CTR 100 % to 200 %, DIP-4, 400 mil
TCET1104G	CTR 160 % to 320 %, DIP-4, 400 mil
TCET1105G	CTR 50 % to 150 %, DIP-4, 400 mil
TCET1106G	CTR 100 % to 300 %, DIP-4, 400 mil
TCET1107G	CTR 80 % to 160 %, DIP-4, 400 mil
TCET1108G	CTR 130 % to 260 %, DIP-4, 400 mil
TCET1109G	CTR 200 % to 400 %, DIP-4, 400 mil

Note

G = lead form 10.16 mm; G is not marked on the body

ABSOLUTE MAXIMUM RATINGS ⁽¹⁾				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
INPUT				
Reverse voltage		V_R	6	V
Forward current		I_F	60	mA
Forward surge current	$t_p \leq 10 \mu s$	I_{FSM}	1.5	A
OUTPUT				
Collector emitter voltage		V_{CEO}	70	V
Emitter collector voltage		V_{ECO}	7	V
Collector current		I_C	50	mA
Collector peak current	$t_p/T = 0.5, t_p \leq 10 ms$	I_{CM}	100	mA
COUPLER				
Isolation test voltage (RMS)	$t = 1 min$	V_{ISO}	5000	V_{RMS}
Operating ambient temperature range		T_{amb}	- 40 to + 100	°C
Storage temperature range		T_{stg}	- 55 to + 125	°C
Soldering temperature ⁽²⁾	2 mm from case, $\leq 10 s$	T_{sld}	260	°C

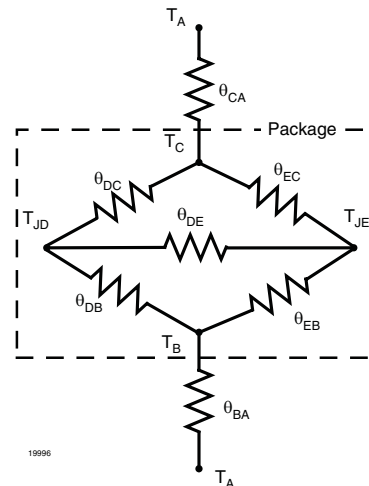
Notes

⁽¹⁾ $T_{amb} = 25 \text{ }^\circ\text{C}$, unless otherwise specified.

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability.

⁽²⁾ Refer to wave profile for soldering conditions for through hole devices (DIP).

THERMAL CHARACTERISTICS (1)			
PARAMETER	SYMBOL	VALUE	UNIT
LED power dissipation	P_{diss}	100	mW
Output power dissipation	P_{diss}	150	mW
Maximum LED junction temperature	$T_{jmax.}$	125	°C
Maximum output die junction temperature	$T_{jmax.}$	125	°C
Thermal resistance, junction emitter to board	θ_{EB}	173	°C/W
Thermal resistance, junction emitter to case	θ_{EC}	149	°C/W
Thermal resistance, junction detector to board	θ_{DB}	111	°C/W
Thermal resistance, junction detector to case	θ_{DC}	127	°C/W
Thermal resistance, junction emitter to junction detector	θ_{ED}	173	°C/W
Thermal resistance, board to ambient (2)	θ_{BA}	197	°C/W
Thermal resistance, case to ambient (2)	θ_{CA}	4041	°C/W



Note

(1) The thermal model is represented in the thermal network below. Each resistance value given in this model can be used to calculate the temperatures at each node for a given operating condition. The thermal resistance from board to ambient will be dependent on the type of PCB, layout and thickness of copper traces. For a detailed explanation of the thermal model, please reference Vishay's "Thermal Characteristics of Optocouplers" application note.

(2) For 2 layer FR4 board (4" x 3" x 0.062").

ELECTRICAL CHARACTERISTICS						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
INPUT						
Forward voltage	$I_F = 50 \text{ mA}$	V_F		1.25	1.6	V
Junction capacitance	$V_R = 0, f = 1 \text{ MHz}$	C_j		50		pF
OUTPUT						
Collector emitter voltage	$I_C = 1 \text{ mA}$	V_{CEO}	70			V
Emitter collector voltage	$I_E = 100 \mu\text{A}$	V_{ECO}	7			V
Collector emitter cut-off current	$V_{CE} = 20 \text{ V}, I_F = 0 \text{ A}, E = 0$	I_{CEO}		10	100	nA
COUPLER						
Collector emitter saturation voltage	$I_F = 10 \text{ mA}, I_C = 1 \text{ mA}$	V_{CEsat}			0.3	V
Cut-off frequency	$V_{CE} = 5 \text{ V}, I_F = 10 \text{ mA}, R_L = 100 \Omega$	f_c		110		kHz
Coupling capacitance	$f = 1 \text{ MHz}$	C_k		0.3		pF

Note

$T_{amb} = 25 \text{ }^\circ\text{C}$, unless otherwise specified.

Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements.



CURRENT TRANSFER RATIO							
PARAMETER	TEST CONDITION	PART	SYMBOL	MIN.	TYP.	MAX.	UNIT
I_C/I_F	$V_{CE} = 5\text{ V}, I_F = 1\text{ mA}$	TCET1101 TCET1101G	CTR	13	30		%
		TCET1102 TCET1102G	CTR	22	45		%
		TCET1103 TCET1103G	CTR	34	70		%
		TCET1104 TCET1104G	CTR	56	90		%
	$V_{CE} = 5\text{ V}, I_F = 5\text{ mA}$	TCET1100 TCET1100G	CTR	50		600	%
		TCET1105 TCET1105G	CTR	50		150	%
		TCET1106 TCET1106G	CTR	100		300	%
		TCET1107 TCET1107G	CTR	80		160	%
		TCET1108 TCET1108G	CTR	130		260	%
	$V_{CE} = 5\text{ V}, I_F = 10\text{ mA}$	TCET1109 TCET1109G	CTR	200		400	%
		TCET1101 TCET1101G	CTR	40		80	%
		TCET1102 TCET1102G	CTR	63		125	%
TCET1103 TCET1103G		CTR	100		200	%	
		TCET1104 TCET1104G	CTR	160		320	%

MAXIMUM SAFETY RATINGS						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
INPUT						
Forward current		I_F			130	mA
OUTPUT						
Power dissipation		P_{diss}			265	mW
COUPLER						
Rated impulse voltage		V_{IOTM}			6	kV
Safety temperature		T_{si}			150	°C

Note

According to DIN EN 60747-5-5 (see figure 2). This optocoupler is suitable for safe electrical isolation only within the safety ratings. Compliance with the safety ratings shall be ensured by means of suitable protective circuits.

INSULATION RATED PARAMETERS						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Partial discharge test voltage - routine test	100 %, $t_{test} = 1\text{ s}$	V_{pd}	1.6			kV
Partial discharge test voltage - lot test (sample test)	$t_{Tr} = 60\text{ s}, t_{test} = 10\text{ s},$ (see figure 2)	V_{IOTM}	6			kV
		V_{pd}	1.3			kV
Insulation resistance	$V_{IO} = 500\text{ V}$	R_{IO}	10^{12}			Ω
	$V_{IO} = 500\text{ V}, T_{amb} = 100\text{ °C}$	R_{IO}	10^{11}			Ω
	$V_{IO} = 500\text{ V}, T_{amb} = 150\text{ °C}$ (construction test only)	R_{IO}	10^9			Ω

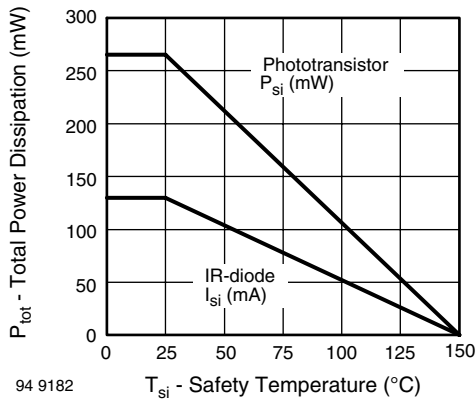


Fig. 1 - Derating Diagram

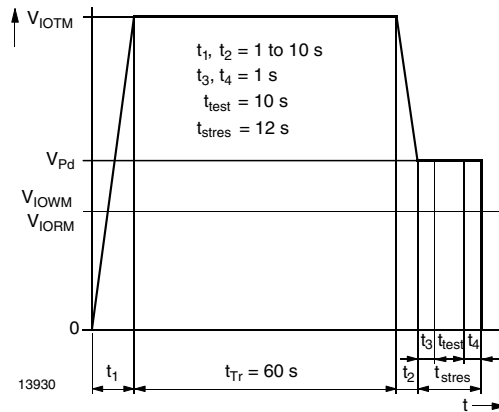
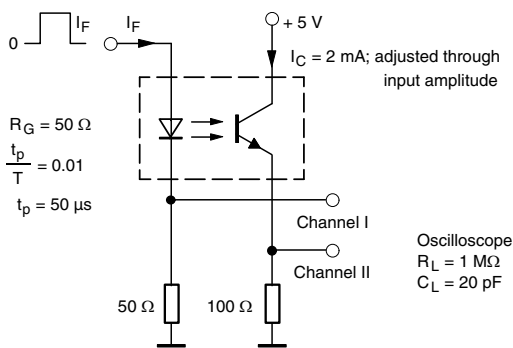


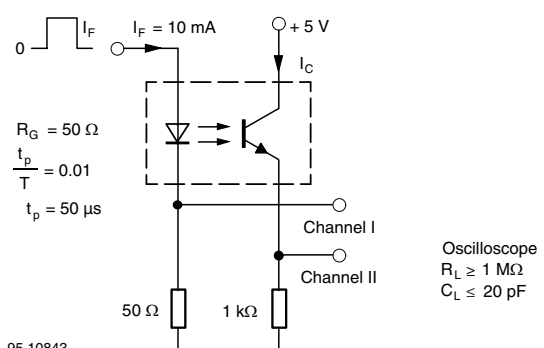
Fig. 2 - Test Pulse Diagram for Sample Test According to
DIN EN 60747-5-5/DIN EN 60747-; IEC 60747

SWITCHING CHARACTERISTICS						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Delay time	$V_S = 5\text{ V}$, $I_C = 2\text{ mA}$, $R_L = 100\ \Omega$, (see figure 3)	t_d		3		μs
Rise time	$V_S = 5\text{ V}$, $I_C = 2\text{ mA}$, $R_L = 100\ \Omega$, (see figure 3)	t_r		3		μs
Turn-on time	$V_S = 5\text{ V}$, $I_C = 2\text{ mA}$, $R_L = 100\ \Omega$, (see figure 3)	t_{on}		6		μs
Storage time	$V_S = 5\text{ V}$, $I_C = 2\text{ mA}$, $R_L = 100\ \Omega$, (see figure 3)	t_s		0.3		μs
Fall time	$V_S = 5\text{ V}$, $I_C = 2\text{ mA}$, $R_L = 100\ \Omega$, (see figure 3)	t_f		4.7		μs
Turn-off time	$V_S = 5\text{ V}$, $I_C = 2\text{ mA}$, $R_L = 100\ \Omega$, (see figure 3)	t_{off}		5		μs
Turn-on time	$V_S = 5\text{ V}$, $I_F = 10\text{ mA}$, $R_L = 1\text{ k}\Omega$, (see figure 4)	t_{on}		9		μs
Turn-off time	$V_S = 5\text{ V}$, $I_F = 10\text{ mA}$, $R_L = 1\text{ k}\Omega$, (see figure 4)	t_{off}		10		μs



95 10804

Fig. 3 - Test Circuit, Non-Saturated Operation



95 10843

Fig. 4 - Test Circuit, Saturated Operation

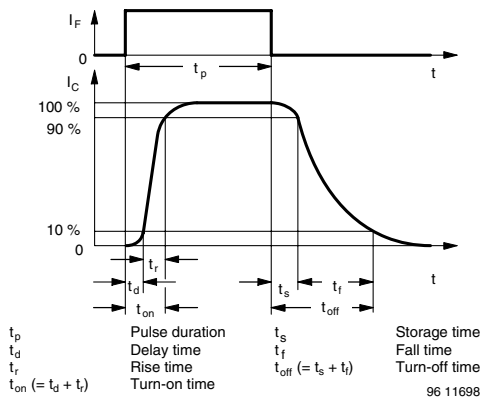


Fig. 5 - Switching Times

TYPICAL CHARACTERISTICS

$T_{amb} = 25\text{ }^\circ\text{C}$, unless otherwise specified

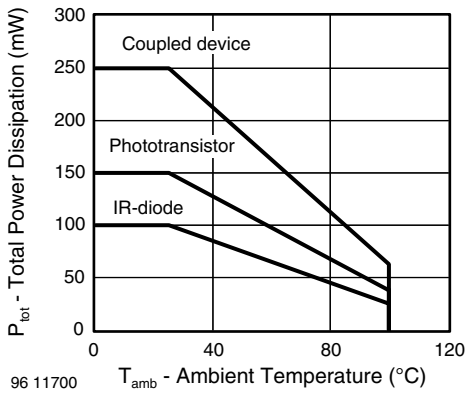


Fig. 6 - Total Power Dissipation vs. Ambient Temperature

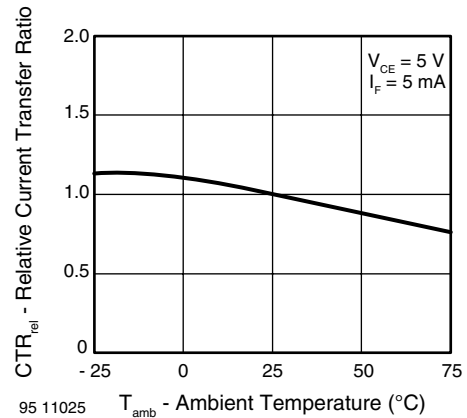


Fig. 8 - Relative Current Transfer Ratio vs. Ambient Temperature

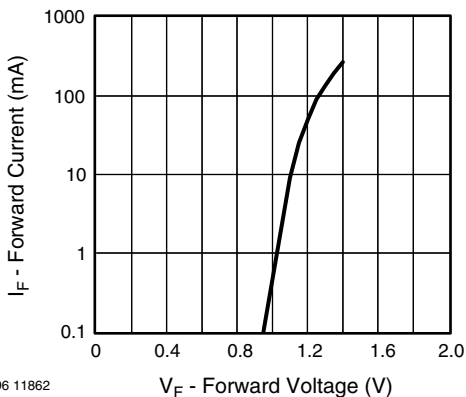


Fig. 7 - Forward Current vs. Forward Voltage

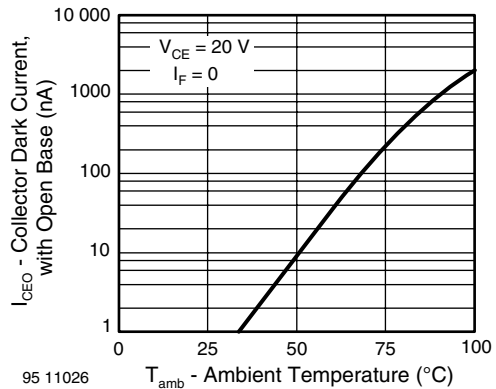
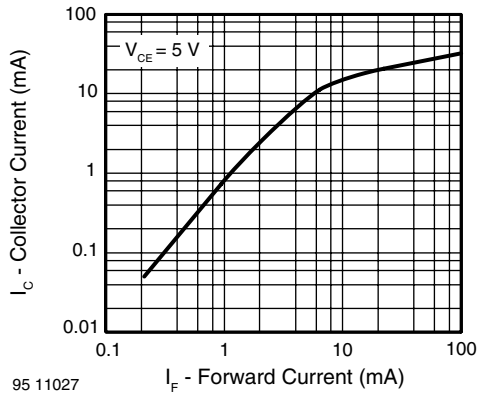
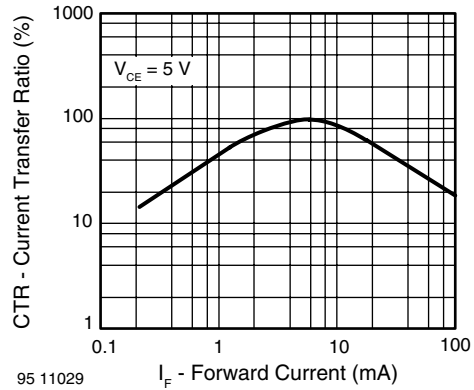


Fig. 9 - Collector Dark Current vs. Ambient Temperature



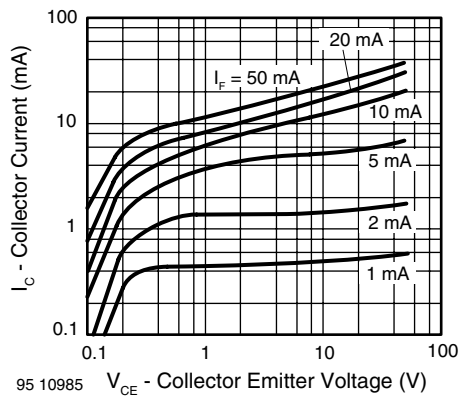
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Fig. 10 - Collector Current vs. Forward Current



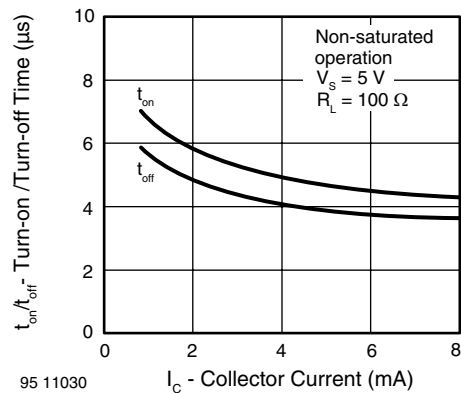
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Fig. 13 - Current Transfer Ratio vs. Forward Current



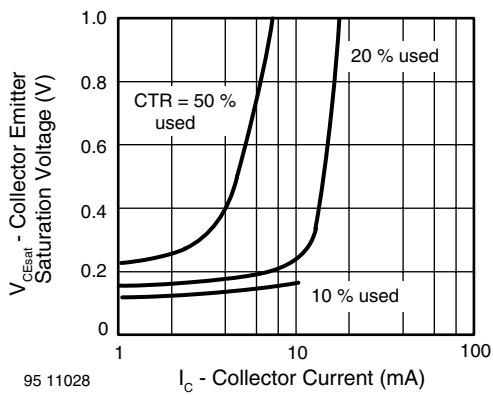
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Fig. 11 - Collector Current vs. Collector Emitter Voltage



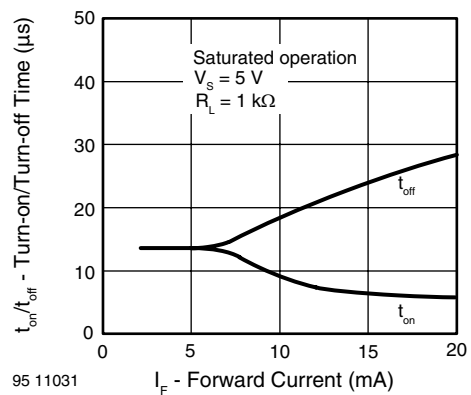
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Fig. 14 - Turn-on/off Time vs. Collector Current



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Fig. 12 - Collector Emitter Saturation Voltage vs. Collector Current



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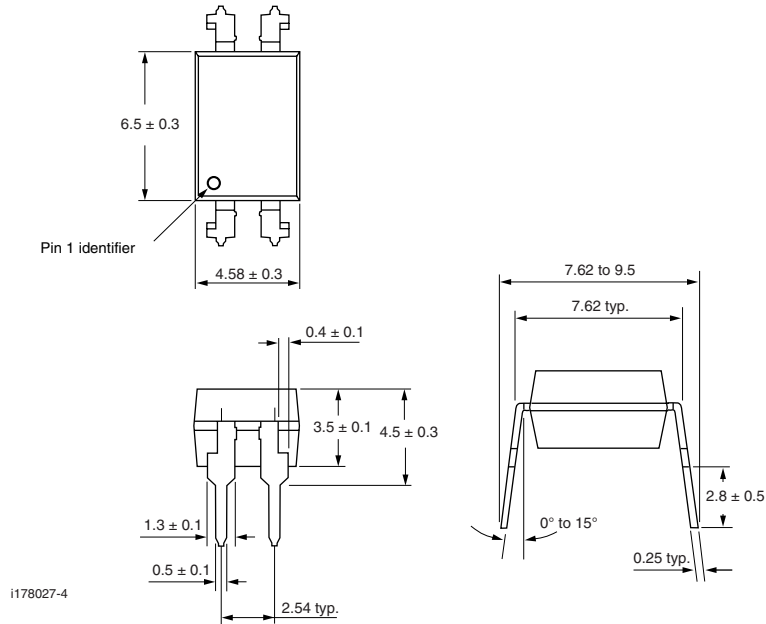
Fig. 15 - Turn-on/off Time vs. Forward Current



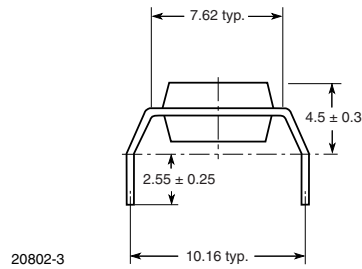
TCET1100, TCET1100G

Optocoupler, Phototransistor Output, Vishay Semiconductors
High Temperature

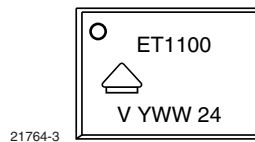
PACKAGE DIMENSIONS in millimeters



TCET1100G type



PACKAGE MARKING





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